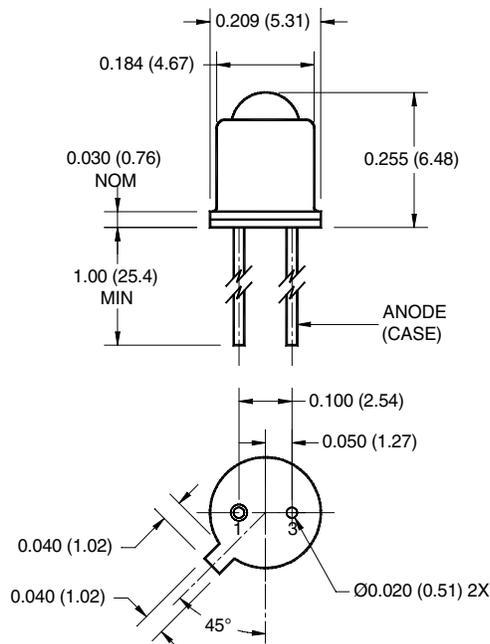


PACKAGE DIMENSIONS



NOTES:

1. Dimensions for all drawings are in inches (mm).
2. Tolerance of $\pm .010 (.25)$ on all non-nominal dimensions unless otherwise specified.

FEATURES

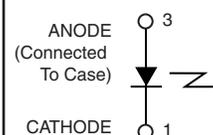
- Good optical to mechanical alignment
- Mechanically and wavelength matched to the TO-18 series phototransistor
- Hermetically sealed package
- High irradiance level
- (*) Indicates JEDEC registered values



DESCRIPTION

- The 1N6264 is a 940 nm LED in a narrow angle, TO-46 package.

SCHEMATIC



1. Derate power dissipation linearly 1.70 mW/°C above 25°C ambient.
2. Derate power dissipation linearly 13.0 mW/°C above 25°C case.
3. RMA flux is recommended.
4. Methanol or isopropyl alcohols are recommended as cleaning agents.
5. Soldering iron tip 1/16" (1.6mm) minimum from housing.
6. As long as leads are not under any stress or spring tension
7. Total power output, P_O, is the total power radiated by the device into a solid angle of 2 π steradians.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise specified)

Parameter	Symbol	Rating	Unit
* Operating Temperature	T _{OPR}	-65 to +125	°C
* Storage Temperature	T _{STG}	-65 to +150	°C
* Soldering Temperature (Iron) ^(3,4,5 and 6)	T _{SOL-I}	240 for 5 sec	°C
* Soldering Temperature (Flow) ^(3,4 and 6)	T _{SOL-F}	260 for 10 sec	°C
* Continuous Forward Current	I _F	100	mA
* Forward Current (pw, 1μs; 200Hz)	I _F	10	A
* Reverse Voltage	V _R	3	V
* Power Dissipation (T _A = 25°C) ⁽¹⁾	P _D	170	mW
Power Dissipation (T _C = 25°C) ⁽²⁾	P _D	1.3	W

ELECTRICAL / OPTICAL CHARACTERISTICS (T_A = 25°C) (All measurements made under pulse conditions)

PARAMETER	TEST CONDITIONS	SYMBOL	MIN	TYP	MAX	UNITS
* Peak Emission Wavelength	I _F = 100 mA	λ _P	935	—	955	nm
Emission Angle at 1/2 Power	I _F = 100 mA	θ	—	±8	—	Deg.
* Forward Voltage	I _F = 100 mA	V _{F1}	—	—	1.7	V
* Reverse Leakage Current	V _R = 3 V	I _R	—	—	10	μA
* Total Power	I _F = 100 mA	P _O	6	—	—	mW
Rise Time 0-90% of output		t _r	—	1.0	—	μs
Fall Time 100-10% of output		t _f	—	1.0	—	μs

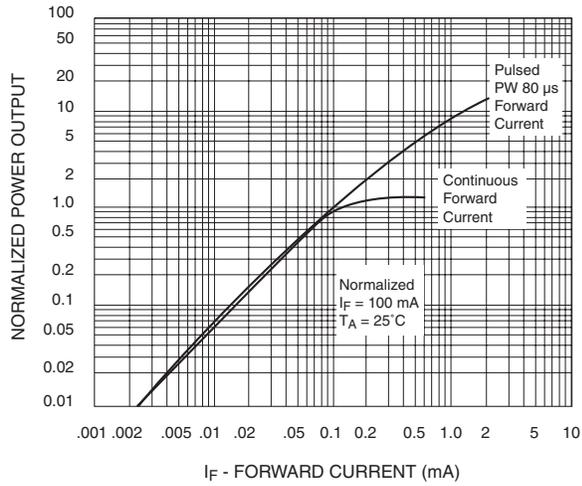


Fig. 1 Power Output vs. Input Current

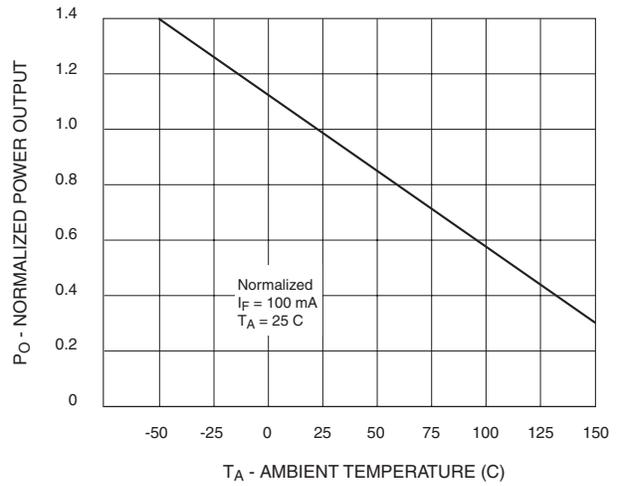


Fig. 2 Power Output vs. Temperature

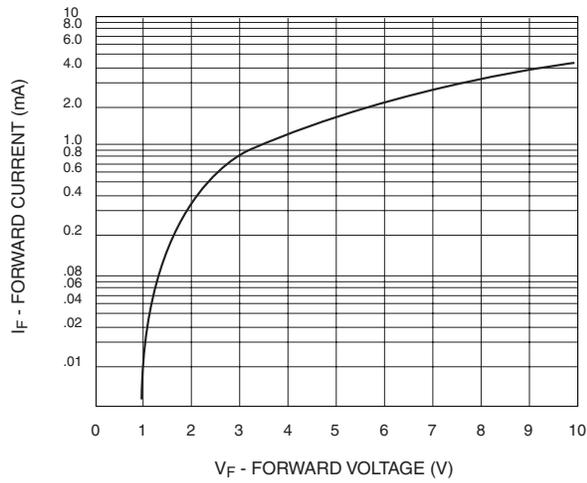


Fig. 3 Forward Voltage vs. Forward Current

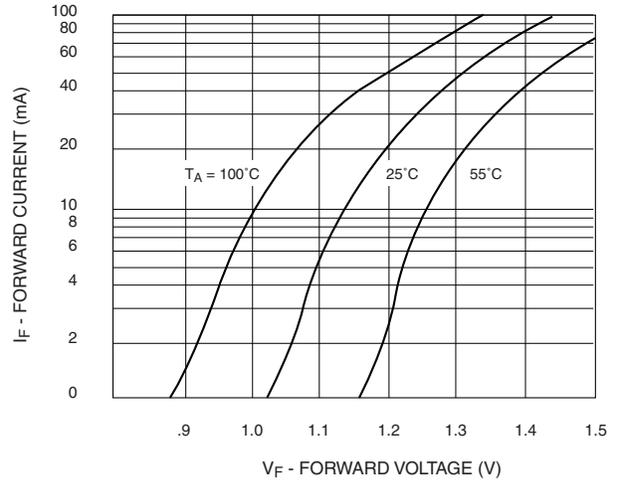


Fig. 4 Forward Voltage vs. Forward Current

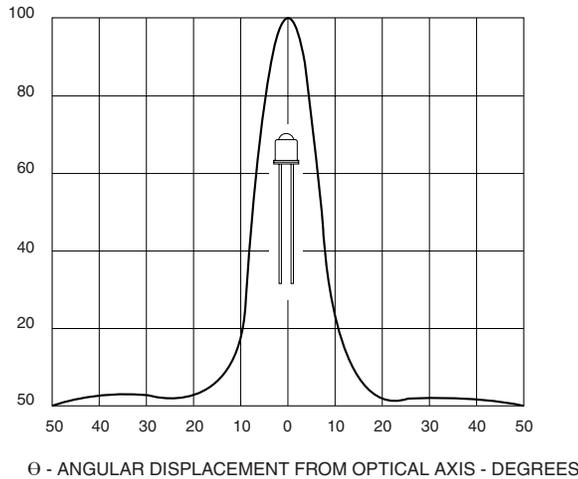


Fig. 5 Typical Radiation Pattern

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